

GP1A73AJ000F

Gap : 5mm Slit : 0.5mm
*OPIC Output,
Snap-in type
Transmissive Photointerrupter with
Connector



■ Description

GP1A73AJ000F is a standard, OPIC output, transmissive photointerrupter with opposing emitter and detector in a case, providing non-contact sensing. For this family of devices, the emitter and detector are inserted in a case, and a 3-pin connector is included to allow remote-mount or off-board designs.

■ Features

1. Transmissive with OPIC output
2. Highlights :
 - Special position hooks compatible with 3 different plate thicknesses (1.0, 1.2, 1.6mm)
 - Hinged snap insertion
3. Key Parameters :
 - Gap Width : 5mm
 - Slit Width (detector side): 0.5mm
 - Package : 17×12.8×8mm (without connector and hooks)
 - Connector : Tyco Electronics AMP K.K. (PN : 292133-3) or SUMIKO TEC CO., LTD. (PN : GH4A003P000ZA)
 - Output Type : High when the object is present with Pullup Resistor.
4. Lead free and RoHS directive compliant

■ Agency approvals/Compliance

1. Compliant with RoHS directive

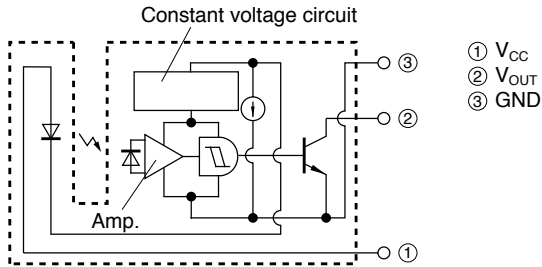
■ Applications

1. General purpose detection of object presence or motion.
2. Example : PPC, FAX, Printer

* "OPIC"(Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and a signal-processing

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■ Internal Connection Diagram

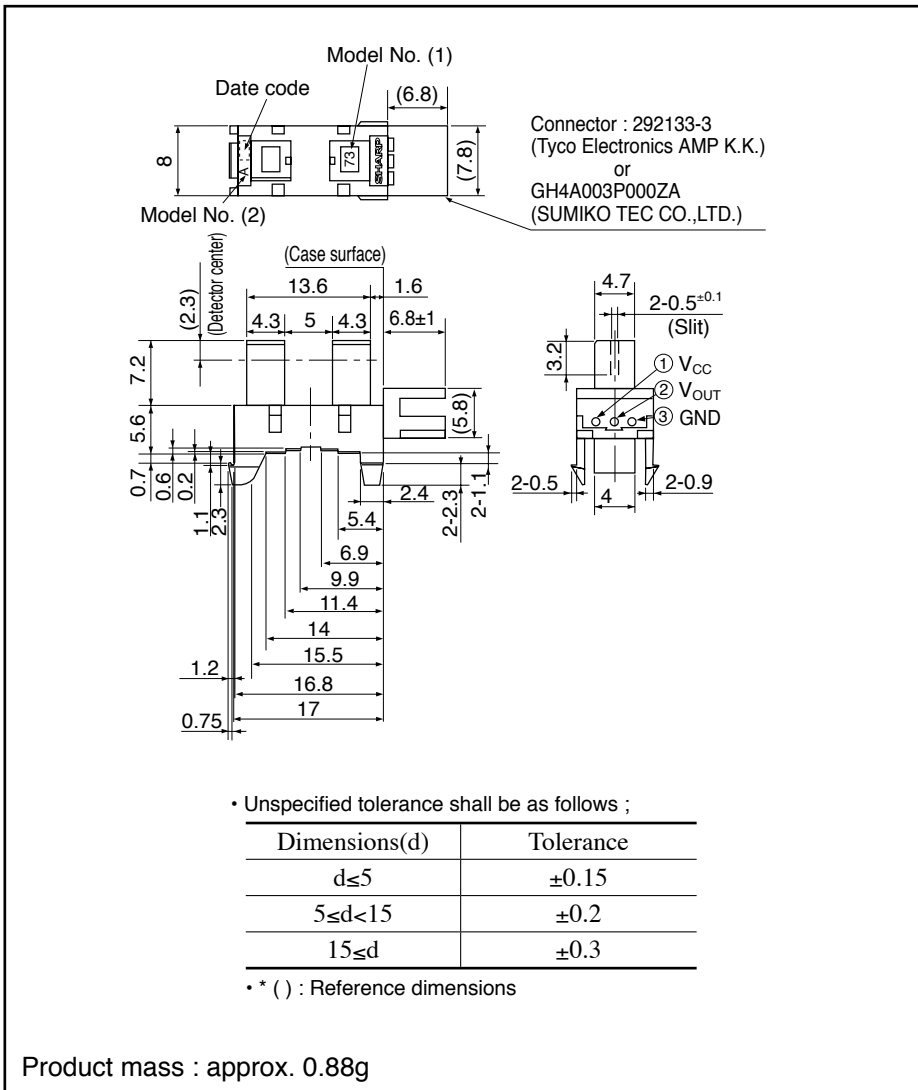


Truth table (In case of external addition pull-up resistance to V_{OUT} terminal)

Condition	Output
Light beam interrupted	High
Light beam uninterrupted	Low

■ Outline Dimensions

(Unit : mm)



Connector terminal plating material : Sn (PN : 292133-3)
or SnCu (PN : GH4A003P000ZA)

Date code (2 digit)

1st digit		2nd digit	
Year of production		Month of production	
A.D.	Mark	Month	Mark
2000	0	1	1
2001	1	2	2
2002	2	3	3
2003	3	4	4
2004	4	5	5
2005	5	6	6
2006	6	7	7
2007	7	8	8
2008	8	9	9
2009	9	10	X
2010	0	11	Y
:	:	12	Z

repeats in a 10 year cycle

Country of origin

Japan or Philippines

(Indicated on the packing case)

■ Absolute Maximum Ratings (T_a=25°C)

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.5 to +7	V
*1 Output voltage	V _{OUT}	-0.5 to +7	V
*2 Output current	I _{OL}	8	mA
*3 Operating temperature	T _{opr}	-20 to +75	°C
*3 Storage temperature	T _{stg}	-30 to +85	°C

*1 Collector-emitter voltage of output transistor.

*2 Collector current of output transistor, refer to Fig.1.

*3 The connector should be plugged in/out at normal temperature.

■ Electro-optical Characteristics (V_{CC}=5V, T_a=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Low level supply current		I _{CCL}	Light beam uninterrupted	-	-	16.5	mA
Low level output voltage		V _{OL}	Light beam uninterrupted, I _{OL} =4mA	-	-	0.35	V
High level supply current		I _{CCH}	Light beam interrupted	-	-	16.5	mA
High level output voltage		V _{OH}	Light beam interrupted, R _L =47kΩ	V _{CC} ×0.9	-	-	V
Operating supply voltage		V _{CC}	-	4.5	-	5.5	V
Response characteristics	Min. interrupted time	t _H	R _L =4.7kΩ	166	-	-	μs
	Min. uninterrupted time	t _L		166	-	-	

Fig.1 Output Current vs. Ambient Temperature

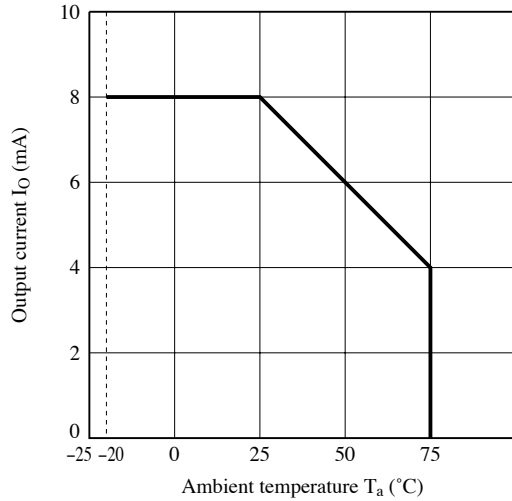


Fig.2 Low Level Output Voltage vs. Low Level Output Current

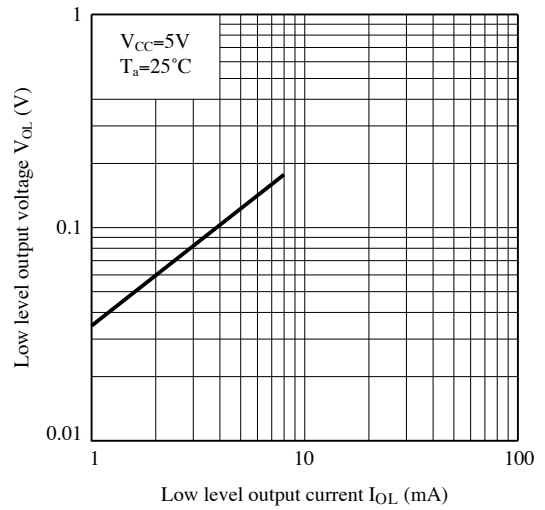


Fig.3 Low Level Output Voltage vs. Ambient Temperature

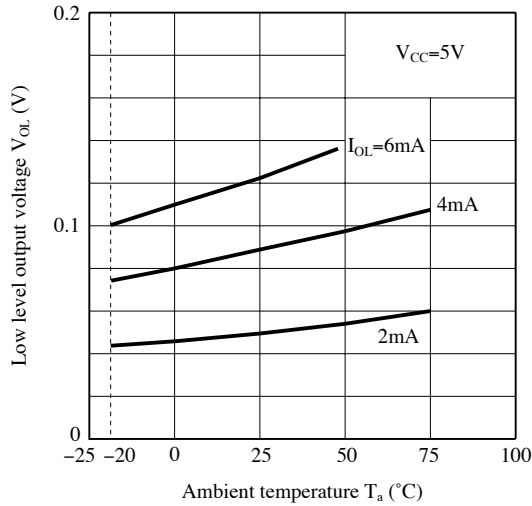


Fig.4 Supply Current vs. Supply Voltage

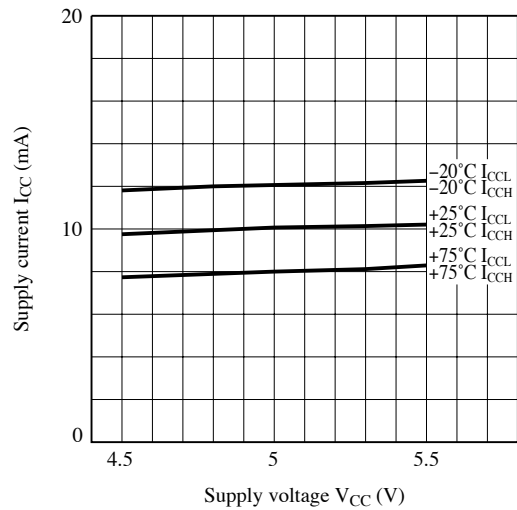


Fig.5 Detecting Position Characteristics (1)

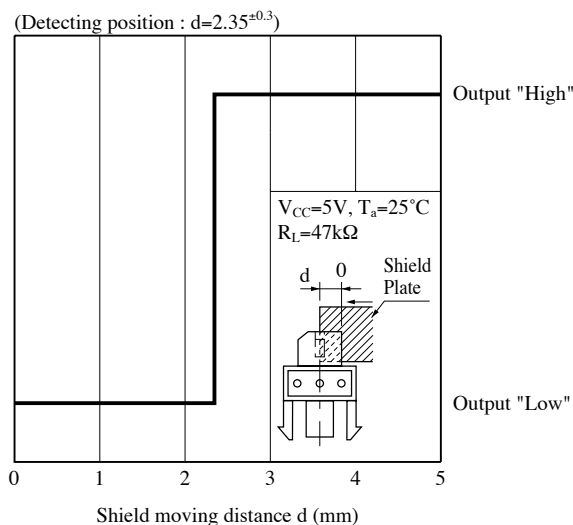
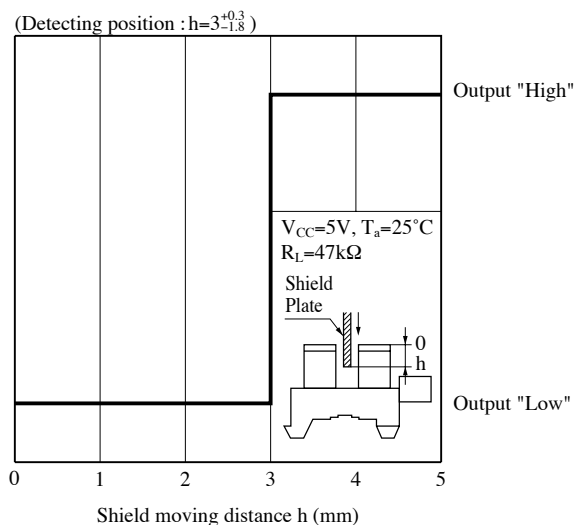


Fig.6 Detecting Position Characteristics (2)



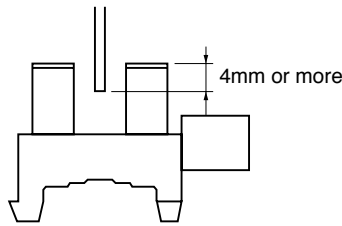
Remarks : Please be aware that all data in the graph are just for reference and not for guarantee.

■ **Design Considerations**

● **Design guide**

- 1) Prevention of detection error
To prevent photointerrupter from faulty operation caused by external light, do not set the detecting face to the external light.
- 2) In order to stabilize power supply line, connect aby-pass capacitor of more than 0.01 μ F between V_{CC} and GND near the device.
- 3) When the sensor is connected with long wire, noise might be on the signal from the sensor while it is going through the wire. To avoid this problem, please evaluate the sensor under actual usage condition to make sure that the system works fine.
- 4) Position of opaque board
Opaque board shall be installed at place 4mm or more from the top of elements.

(Example)



This product is not designed against irradiation and incorporates non-coherent IRED.

● **Parts**

This product is assembled using the below parts.

- Photodetector (qty. : 1) [Using a silicon photodiode as light detecting portion, and a bipolar IC as signal processing circuit]

Category	Material	Maximum Sensitivity wavelength (nm)	Sensitivity wavelength (nm)	Response time (μ s)
Photodiode	Silicon (Si)	900	400 to 1 200	10

- Photo emitter (qty. : 1)

Category	Material	Maximum light emitting wavelength (nm)	I/O Frequency (MHz)
Infrared emitting diode (non-coherent)	Gallium arsenide (GaAs)	940	0.3

- Material

Case	Lead frame	Connector terminal finish
Black polycarbonate resin (UL94V-2)	42Alloys (There is no plating)	Sn plating (PN : 292133-3) SnCu plating (PN : GH4A003P000ZA)

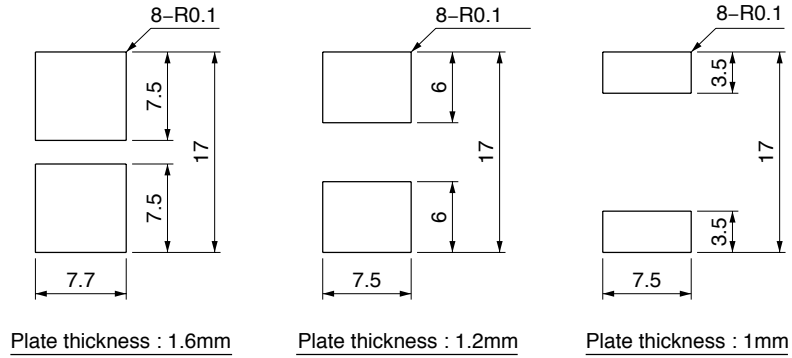
- Others

Laser generator is not used.

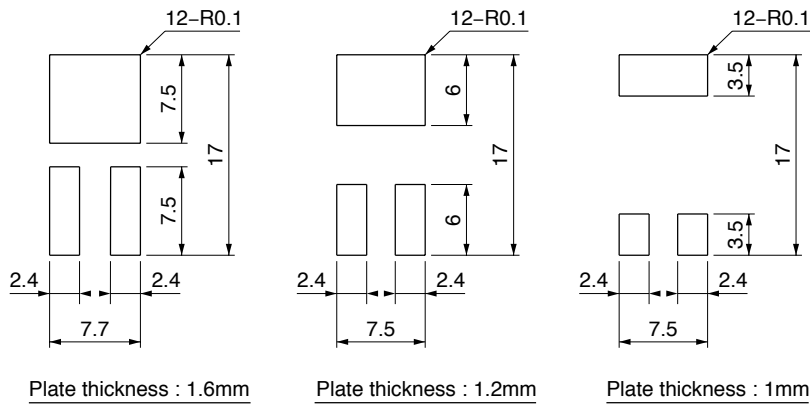
● **Recommended Installation Hole drawing**

- 1) We recommend to fix the product at punching side on the fixing plate (metal plate).
- 2) Please decide the final dimensions at your side after confirmation by the actual applications. Because mounting efficiency and mounted stabilization are dependent on mounting hole corner curve and punched state.
- 3) Tolerance shall be $\pm 0.1\text{mm}$

Normal type



Reverse-insertion prevention type



■ Manufacturing Guidelines**● Notes of cleaning**

Please carry out neither the immersion cleaning nor the ultrasonic cleaning to avoid the solvent residue inside the case.

When necessary, dust and stain shall clean by air-blow or wipe off by soft cloth soaked in cleaning agent. The cleaning agent used to wipe off must use only the following kind. Ethyl alcohol, Methyl alcohol and Iso-propyl alcohol.

● Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

•Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

■ Package specification**● Case package****Package materials**

Anti-static plastic bag : Polyethylene

Moltopren : Urethane

Partition : Corrugated fiberboard

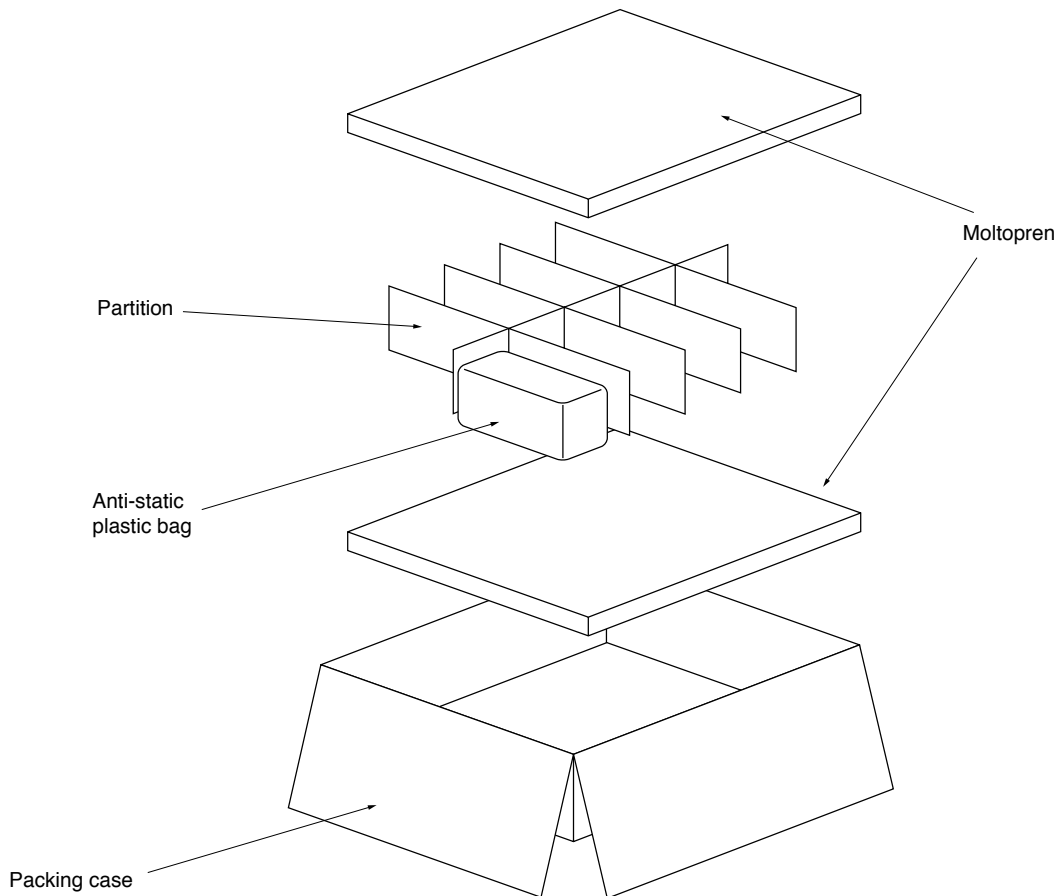
Packing case : Corrugated fiberboard

Package method

100 pcs of products shall be packaged in a plastic bag, Ends shall be sealed by stapler. The bottom of the packing case is covered with moltopren, and the partition is set in the packing case. Each partition should have 1 plastic bag.

The 10 plastic bags containing a product are put in the packing case.

Moltopren should be located after all product are settled (1 packing contains 1 000 pcs).

Packing composition

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- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

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- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

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- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
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